

Title (en)

DRESSING TOOL, DRESSING DEVICE, DRESSING METHOD, PROCESSING DEVICE, AND SEMICONDUCTOR DEVICE PRODUCING METHOD

Title (de)

RICHTWERKZEUG, RICHTVORRICHTUNG, RICHTVERFAHREN, BEARBEITUNGSVORRICHTUNG UND VERFAHREN ZUR HERSTELLUNG EINER HALBLEITERANORDNUNG

Title (fr)

OUTIL, DISPOSITIF ET PROCEDE DE FINISSAGE, DISPOSITIF DE TRAITEMENT ET PROCEDE DE PRODUCTION DE DISPOSITIF A SEMICONDUCTEURS

Publication

**EP 1426140 A4 20070808 (EN)**

Application

**EP 02765417 A 20020905**

Priority

- JP 0209022 W 20020905
- JP 2001272945 A 20010910
- JP 2002058096 A 20020304
- JP 2002175035 A 20020614

Abstract (en)

[origin: EP1426140A1] A dressing apparatus DA is constructed from a pad holding mechanism 10 which holds a polishing pad 15 that has a doughnut disk-form pad surface 15a, and which causes this polishing pad 15 to rotate, a dressing tool 2 which has a substantially rectangular dressing surface 3, and a dressing tool holding mechanism 1 which holds the dressing tool 2 so that the dressing surface 3 of this dressing tool 2 is caused to face the pad surface 15a of the polishing pad 15 that is held and caused to rotate by the pad holding mechanism 10. The dressing tool holding mechanism 1 causes the held dressing tool 2 to contact the pad surface 15a in a state in which the centerline L1 in the direction of width of the dressing surface 3 is oriented so that this centerline extends in the radial direction of the pad surface 15a, and thus causes dressing to be performed. As a result, the flatness of the working surface following dressing can be improved. <IMAGE>

IPC 1-7

**B24B 53/12**; **B24B 53/02**; **B24B 37/00**; **H01L 21/304**

IPC 8 full level

**B24B 53/007** (2006.01); **B24B 53/017** (2012.01)

CPC (source: EP KR US)

**B24B 53/017** (2013.01 - EP US); **B24B 53/12** (2013.01 - KR)

Citation (search report)

- No further relevant documents disclosed
- See references of WO 03022523A1

Cited by

US2012058716A1; US9108294B2

Designated contracting state (EPC)

DE FR GB NL

DOCDB simple family (publication)

**EP 1426140 A1 20040609**; **EP 1426140 A4 20070808**; **EP 1426140 B1 20130710**; CN 1553842 A 20041208; KR 100565913 B1 20060331; KR 20040031070 A 20040409; TW 546182 B 20030811; US 2005032467 A1 20050210; US 2006292969 A1 20061228; WO 03022523 A1 20030320

DOCDB simple family (application)

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